

3U Rackmount Chassis

Flexible Configuration

Backplane Connector
Easy Maintenance System with Cableless Design

High Density and Performance

IPC-H3D470 Chassis Specs

IPC-H3D470 Chassis Specs	
Model	IPC-H3D470
Form Factor	3U
Configuration	CPU:I7-10700 4.8GHZ, 8 cores and 16 threads. Memory: 16GB DDR4 2666
GPIO	8 x GPI, 8 x GPO, (shared with LPT header)
Ethernet	2 x LAN: Intel® I219V with 10/100/1000 Mbps,support AMT/vPro
Ports	Front:2xUSB2.0; Rear:2xUSB2.0; 4xUSB3.0; 4xfast 232/422/485 serial ports; 1xVGA, 1xHDMI, 1xDVI 1x DP, High Definition Audio, Line-In/ Line-Out/ Mic-In
TPM	On board
PSU	850W server ATX power supply
Cooling Fans	2x Hot-Swappable 8038mm(option 1x 8038mm)
Fans Failure Alarm	Yes
PCIE	1 x PCI-E 3.0 x16 slots,1 x PCI-E 3.0 x8 slots,3 x PCI-E 3.0 x4 slots; 2 x PCI
HDD	1T SATA 7200 Seagate hard drive * 2
Graphics card Support	Support full size NVIDIA GeForce RTX 3060
Slide Rail	Included
Power input	100-230V, 50/60Hz
Indicators	1x Power Status, 1x HDD Activity, 2x LAN Activity, 1x Failure
Front Buttons	Power On/Off, System Reset
Metal Thickness	1mm SGCC
Dimension	53 x 437.5 x 133cm (D x W x H)
Working temperature	0°C ~ 60°C
Weight(LBS)	NW:23.14 GW:36
Certification	CE/FCC/RoHS

